E Series Enhanced Manual Probe Station

An enhanced wafer test equipment for laboratory applications

1、Product Overview

The E series is a functionally advanced probe station capable of electrode Pad testing above 1µm. With an easy-to-operate ergonomic design and flexible UPStart[™] modular design, customers can upgrade more test functions such as mmW, FA, MEMS, WLR, and optoelectronic testing with minimum cost.

>Main Features

1. More flexible UPStart[™] modular design with richer optional configurations, including chuck, needle holder, probe, fixtures, microscope, anti-vibration table, shielding box, and other options.

2. Large body structure for enhanced operating comfort and a larger platform for probe holders and probe card support to improve the accuracy of contact.

3. The chuck can be lifted and adjusted to facilitate quick sample separation from the probe.

4. Standard equipped with the metallographic microscope provides magnification for more than 1μ m electrode

Pad size. It can also carry laser for FA failure analysis/laser cutting.

5. Pneumatic quick lift of microscope provides easy access to change microscope and probe chuck fixture.

>Test application

				High power/H	igh voltage/high current test	•
	Silicon optical device test	\bigcirc	ion		THz and load traction test	0
测试器件	RF device	•	olicat	olicat RF	mmW/sub THz test	•
	LCD -TFT test Storage device (fast pulse test) test	•	t app	WLR、aging to	est	•
	PCB component test	•	Tes	Device charact	evice characterization test	
	LD (VSCEL) PD、LED optoelectronic device test	evice test EL) PD、LED optoelectronic st		FA failure analysis test		
	MEMS device test			1/f Noise test		
	Power device (IGBT, MOSFET) test	•		DC/ (IV、CV) test		
	Wafer level diode and triode test	•		DC/ (IV, CV) test		•

ullet Support Recommended, ullet Support but not recommended, \bigcirc Not supported N/A





2, Product Structure

Microscope

- Compatible with metallographic microscope/monocular video microscope with high magnification/high-resolution objective lens up to μ m/sub- μ m level.

• LED coaxial / ring illumination, high contrast, can load laser for failure analysis/laser cutting

• Microscope pneumatic quick lift + X-Y translation table can adjust the microscope in the X-Y plane 2"×2" range of movement with the accuracy of 1µm, travel 50mm, one-button quick operation, easy and quick replacement of the microscope and probe card fixture which can be customized for incline lift.

Chuck

• Using central and multi-loop vacuum adsorption rings to fix the sample, and each vacuum channel is independently controlled

- Chuck is an electrically independent suspension with a banana head socket, which can be used as a back electrode
- Optional multi-hole adsorption Chuck or high and

low-temperature carrier system; coaxial /triaxial /gold-plated chucks are available.

Chuck multi-stage adsorption channel control switch

• The centralized arrangement and independent control of different channels of adsorption holes

Chuck moving stage - X/Y stroke adjustment

- Chuck fine adjustment lift of 5mm stroke with the precision of $10 \mu \text{m}$

• The chuck table can adopt quick adjustment mode in X/Y direction corresponding to the size of the chuck with the precision of 1um, and all with a locking knob

• Chuck X/Y axis for clearance-free movement, each rotation of a turn of travel for 1mm

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• Chuck rotation angle: 360 degrees, fine-tuning rotation angle





3、Specification parameters

Model		E4	E6	E8	E12		
Shape (L*W*H/mm)		680*670*760	680*670*760	750*670*800	1030*800*850		
About Weight (KG)		90kg	95kg	110kg	210kg		
Power	requirement		22	0VC,50~60Hz			
	Chuck size	4''	6"	8"	12"		
Chuck Normal	Sample fixing method	Annular va	Annular vacuum adsorption (customizable porous adsorption)				
temperature standard	Back electrode test	Yes, sample stage electrically independent overhang					
	Chuck material	316# stainle	ess steel (optior	nal brass nickel plated	OR gold plated)		
	Theta Stroke	fine-t	360 °rotatio	on (coarse adjustment) 8°, fine-tuning accura	; acy 0.002 °		
Chuck moving	Chuck lift	Chuck f	Chuck table can be quickly lifted up and down 5 mm, fine-tuning lift stroke 6 mm, precision 1 μm				
platform	X-Y Stroke	100*100mm	150*150mm	200*200mm	250*250mm		
	Movement accuracy			10µm			
	Rapid chuck pull-out			N/A			
	Control method	Small knob drive					
	Dimensions(L*W)	550*405	980*480mm				
Probe holder	Distance from chuck to platform	8mm(The upper surface of the chuck and the lower surface of the probe holder platform)					
platform	Maximum number	6		8	10		
	Platform lift	N/A					
	Positioning method	Magnetic adsorption or vacuum adsorption					
	Optical characteristics	Standard PSM-1000 metallurgical microscope / optional (GX-6 metallurgical, body view, video) microscope					
	Lens Specifications	20-2000X					
Optical	Magnification	3 CCD options: 200W (digital) / 500W (digital) / 650W (digital)					
characteristics	CCD Pixels	axis movement stroke 50.8 mm, coaxial knob adjustment, fine tuning accuracy better than 1um					
	Motion control	Microscope 2 inches XY panning table range of movement					
	Microscope travel	1μm					
	X-Y-Z stroke		12mr	m-12mm-12mm			
	Mechanical accuracy		10µ	ım/2μm/0.7μm			
Probe Specifications	Leakage accuracy	Coaxial 1pA/V @ 2 Test co	5 °C; Triaxial 10 onditions: dry e (air dew po	DOfA/V @ 25 °C; Triaxi nvironment for ground int lower than - 40 ° (al 10pA@3kv @25°C, ding shield C)		
	Interface form	Banan	a head / alligat	or clip / coaxial / triaxia	, al interface		

*Specifications and designs are subject to change without notice.



4、Product Selection Guide

1、Microscope-4 kinds of microscope options

1.1 PSM-1000 high magnification metallurgical microscope/loadable laser (standard)

	Optical magnification	2000X (eyepiece*zoom magnification*objective lens)
	Eyepiece	10X
	Zoom	1X~2X
	Objective lens	5X(Operating Distance: 34.0mm,NA:0.14)
		10X(Operating Distance: 33.5mm,NA:0.28)
A A A A A A A A A A A A A A A A A A A	(standard)	20X(Operating Distance: 20mm,NA:0.42)
	Objective lens (optional) Microscope focusing	2X(Operating Distance: 34mm,NA:0.055)
North Contraction		50X(Operating Distance: 13mm,NA:0.55)
and the second s		100X(Operating Distance: 3mm,NA:0.8)
		Z-axis travel 50.8 mm, coaxial knob adjustment, fine
	mechanism	tuning accuracy better than 1µm
412	Converter	4-hole manual objective switching nosewheel (4-hole motorized nosewheel can be customized)
	CCD interface form	1X C Mount
	Illumination system	150W high power white illumination source (sleepless brightness adjustment)

Note: PSM-1000 can be equipped with a laser for FA failure analysis/laser cutting function and camera interface with laser safety positioning pins, leaving a position for mounting laser safety filters in front of the microscope binocular head and providing compensation spacers. The laser and safety filter can be easily installed without a special tool kit.

1.2 GX-6 long working distance metallurgical microscope (optional)

	Optical magnification	2000X (Eyepiece*Zoom magnification*Objective lens)	
	Eyepiece	10X/22X	
	Zoom	1X	
	Objective lens (standard)	2X(Operating Distance: 34.0mm)	
		5X(Operating Distance: 45mm)	
		10X(Operating Distance: 34mm)	
		20X(Operating Distance: 30.8mm)	
		50X(Operating Distance: 20.5mm)	
and the star	Objective lens (optional)	100X(Operating Distance: 12.5mm)	
	Microscope Focusing	Z-axis travel 50.8 mm, coaxial knob adjustment, fine	
	Mechanism	tuning accuracy better than 1 μ m	
	Converter	5-hole manual objective switching nose wheel	



CCD interface form	1X C Mount
Illumination system	Cold light source fiber optic reflector illuminator:12V/150W

1.3 Stereomicroscope/SS-M (optional)



1.4Video Microscope/70XL (optional)



- Microscope optical magnification range: 0.75 5.25X, with 19inch monitor magnification can reach 216X
- Continuous zoom ratio: 7:1
- Resolution: 72 240 lp/mm, highest resolution better than $4\mu m$
- NA value: 0.0240 0.080
- Depth of field: 0.98 0.09 mm
- Field of view at low magnification: 6.40 x 8.53 mm
- Field of view at high magnification: 0.91 x 1.22 mm
- Working distance: 89mm
- 150W high power white illumination source (sleepless brightness adjustment)
- Microscope focus mechanism: Z-axis travel 50.8 mm



2、CCD camera - 2 options

Model Parameters







Features	 Image sampling frame rate: 60fps/second high-speed image capture, no dragging, delay phenomenon. New color algorithm to ensure true image color reproduction. 8:8:824bits true color image. HDMI pure digital HD output, supporting 16:9 display. Colors can be adjusted independently, with a unique multi-level wide dynamic (HDR) function. With cross center line, movable line function overlay function with edge enhancement mode enhances special image effects. 	 Adopt 2 million dynamic range Support for predetated v3.0 Support manner one-touch blue adjust Provide 100 Provide 100 Provide 100 Provides meand position Take picture provides meand position Support for Conduct end of the settings up

• Adopt 2 million pixels Sony new generation high dynamic range CMOS 1/2 inch image sensor.

- Support for photo and video recording, built-in latest V3.0 measurement software.
- Support manual one-touch exposure, manual one-touch white balance, and red, green, and blue adjustment.
- Provide 100 lines of drawing function, line color, and position adjustment.
- Take pictures without shaking images and provides more clarity.
- Support for Chinese and English menu language (default English). It can save the parameters settings upon shutdown.

3、Normal temperature standard chucks options

BNC(m)
′ 8"
ess steel/brass nickel plating (gold plating optional)
enter pinhole and vacuum groove
uck: 4, 27, 45, 69, 93, 117 mm uck: 4, 27, 45, 69, 93, 117, 141 mm uck: 4, 27, 45, 69, 93, 117, 141, 164, 195 mm
ge vacuum adsorption control
e grain 4×4mm, or 50mm to 200mm wafer
m
m/10N at the edge of the chuck
ates at -200V to +200V DC
DC
2

3.1 Normal temperature coaxial chucks (Coax)



3.2 Normal temperature triple axis chucks (Triax)

Technical parameters (Triax)	
Interface Type	Triax(m)
Product Diameter	4"/6"/8"
Material	Stainless steel/gold plated brass (gold plated optional)
Chuck surface	Vacuum-absorbed pinhole in the center of the plane (0.5 mm)
Vacuum hole cross-section diameter	4" chucks: 4, 27, 45, 69, 93, 117 mm
Vacuum drive	6" chucks: 4, 27, 45, 69, 93, 117, 141 mm
Supported DUT size	8" chucks: 4, 27, 45, 69, 93, 117, 141, 164, 195 mm
Surface flatness	3-stage vacuum clamping control
Rigidity	Single grain 4 x 4 mm, or 50mm to 200 mm wafer
Electrical specifications (Triax)	
Chuck Insulation	Measured at 10V DC>100
Force to guard	>2TΩ
Guard to shield	>7TΩ
Force to shield	>15TΩ

4、Temperature chuck options

Specification	Coaxial heated chucks (Coax)	Triaxial heated chucks (Triax)	3KV heated chucks (Triax)
Temperature range	+25°C to +300°C	+25°C to +200°C	+25°C to +200°C
Temperature control method	Resistance heaters	Resistance heaters	Resistance heaters
Cooling method	water	water	air
Minimum temperature adjustment resolution	0.1°C	0.1°C	0.1°C
Temperature display resolution	0.01°C	0.01°C	0.01°C
Touch screen operation	Yes	Yes	Yes
Temperature stability	±0.1°C	±0.1°C	±0.1°C
Temperature Accuracy	±0.5°C	±0.5°C	±0.5°C
Control method	Low noise DC/PID power supply	Low noise DC/PID power supply	Low noise DC/PID power supply
Communication control interface	RS232C	RS232C	RS232C
Test cable interface	Coaxial cable (BNC)	Triaxial cable (Triax)	SHV triaxial
Chuck surface plating	Nickel/gold plated	Nickel/gold plated	Nickel/gold plated
Temperature sensor	RTD	RTD	RTD



Temperature uniformity	Room temperature heating to 200°C. ±1% for any one zone. Temperature >200°C, ±1.5%			
Surface flatness	<±10µm	<±10µm	<±10µm	
Electrical insulation, coaxial/BNC(m)/SHV triaxial	>5TΩ	>5TΩ	>5TΩ	
Heating rate	25°C to 200°C <28min 200°C to 300°C < 40min	25°C to 200°C < 28min	25°C to 200°C < 28min	
Cooling rate	200°C to 25°C <20min	200°C to 25°C <20min	200°C to 25°C <50min	
Leakage current at 10V Kelvin triaxial Test conditions: dry environment for grounding shield (air dew point lower than - 40 ° C)	N/A	<100fA	<400fA	
Residual Capacitance	N/A	<200fF	<1pF	
Maximum voltage between chuck surface and GND	500V	500V	3kV	
Vacuum adsorption type	Ring adsorption (optional porous adsorption)		dsorption)	
Vacuum area	m area Central adsorption, 4"/6"/8"/12"		/12"	

5、Probe - DC/RF/Large Voltage Probe Options

5.1 DC Probe Selection Guide

Specification	Coaxial probes	Triaxial probes	Kelvin probes
Maximum Voltage	500V	500V	500V
Temperature Range	150°C	150°C	-60°C 至 300°C
Leakage current	<10pA	<100fA	<20fA
Interface Type	Coaxial male connector	Triaxial male connector	SSMC female to triaxial connector male
Characteristic impedance	50Ω	50Ω	50Ω
Residual Capacitance	<200fF	<200fF	<200fF
Probe holder material	Brass	Brass	Brass



Probe material	Tungsten wire alloy	Tungsten wire alloy	Tungsten wire alloy
Probe tip size	0.2µm–25µm	0.2µm–25µm	1µm–100µm

5.2 High Voltage / High Current Probe Selection Guide

	High Voltage Probe			High Current Probe
Product Model	SHV-C-3kV	HV-T-3kV	UHV-C-10KV	HC-B-500V
Maximum Voltage	3kV	3kV	10kV	500V
Max. current value	1ADC/30A Pulsed Electric	120mA DC	20mA DC	10A DC/100APulsed Electric
Temperature range	-60°C to 300°C	-60°C to 300°C	-60°C to 300°C	-60°C to 300°C
Leakage current	<200pA@3kV <5pA@10V	<1pA@3kV <100fA@10V	<100pA@10kV	N/A
Interface type	SHV	High pressure triaxial	UHV Coaxial	High Voltage Banana
Probe material	Tungsten Probe	Tungsten Probe	Tungsten Probe	BeCu or Tungsten Probe

5.2 RF Probe Selection Guide







>Calibration substrates

GSG	CS-5	CS-9	CS-10	SC-18
PAD Size	50μΧ50μ	100µX100µ	150µX150µ	300µX300µ
	100µX100µ			
	150μΧ150μ			
Pitch range	75µ-250µ	250µ-600µ	600µ-1250µ	1250µ-2540µ
GS	CS-8	CS-14	CS-11	CS-17
PAD Size	50μΧ50μ	100µX100µ	150µX150µ	300µX300µ
	100µX100µ			
	150μΧ150μ			
Pitch range	50μ-200μ	200µ-400µ	400µ-1250µ	750µ-2540µ
GSG>110GHz	CS-15			
PAD Size	25μΧ25μ			
Pitch range	40µ-150µ(SOLT)			
	30µ-150µ(LRM)			



6、 Probe holders - 3 different accuracy options for probe holders



Specification	X-Y-Z Trip	8 x 8 x 8mm	12 x 12x 12mm	12 x 12x 12mm
	Movement method	Linear movement	Linear movement	Linear movement
	Screw accuracy	700 Thread / Inch	100 Thread / Inch	40 Thread / Inch
	Movement accuracy	0.1 μm	0.7µm	10µm
	Size (L*W*H)	148*120*140	115*100*112	64*47*55
	Weight (g)	1500	1000	175



7、 Probe Fixture - 4 different fixture options

SEMISHARE	Triaxial Tip Holder for triaxial interface	
T2H	Shield box with leakage accuracy up to 100FA	
	Wire length 2m	
	One-way screwdriver for probe installation	×
SEMISHARE	Coax (male) Tip Holder	
C2H	Leakage accuracy up to 10PA	
	Wire length 2m	
	Screwdriver for probe installation	No. 10 August 10
SEMISHARE	L shape Triaxial Tip Holder	\bigcirc
T2L	Leakage accuracy up to 100FA with shield box	
	Wire length 2m	
	Screwdriver for probe installation	
SEMISHARE	L-shape Coax (male) Tip Holder	0
C2L	Leakage accuracy up to 10PA	n h
	Wire length 2m	Ţ
	Screwdriver for probe installation	

8、Vacuum Pumps

>Specifications

- ♦Voltage: AC220V
- ◆Flow rate: 7L/min
- ◆Vacuum level: -60KPa
- ♦Weight: 0.7Kg

>Functions

- Provides a vacuum source.
- ◆Provides vacuum adsorption on the CHUCK to hold the sample in place.
- ♦Use with vacuum adsorption-type micropositioner to fix the probe holder.

>Features

- igodotOil-free and silent, especially suitable for laboratory and clean room use
- ◆7 L/min for 24-hour uninterrupted operation





9、Air-floating automatic balance anti-vibration table

(1) High precision type

The pneumatic support frame is designed and manufactured with a special two-chamber system to keep natural vibration frequency low, provide excellent vibration isolation in vertical and horizontal directions, and excellent damping and automatic leveling.

>Specifications

Reference Size (L*W*H)	600*900*600mm	
Isolation System	Pneumatic isolation	
Resonance frequency	Vertical/horizontal = 1.2 - 3.0 Hz	3
10 Hz Isolation	Vertical/horizontal = 80 - 99%	
Leveling repeatability	Standard leveling valve = ± 1.0 mm (0.04 in.)	10
Maximum load capacity	Precision leveling value = ± 0.05 mm (0.002 in.)	1 Transmitted
Automatic leveling	500 kg	Voceleration
Height adjustment	Yes	10.01
Required air supply	±20 mm	0.001



(2) Economy type

Through a series of design improvements of shock absorption systems, such as the shape and material of the air spring, the volume of the spring chamber and the volume of the auxiliary tank, the damping aperture, and the level adjustment value, etc., it provides good overall stability.

Specifications

•Size: L*W*H(800*800*700mm) (Custom sizes available)

•Load-bearing: 500kg



Note: Anti-vibration table can be used with an economic optical flat panel or high-precision honeycomb panel according to the budget.



10、Lasers (FA failure analysis / laser cutting)

The multi-band laser cutting system can be mounted on most microscopes which can be used for FA (failure analysis), enabling precise cutting at the microscopic level and selective removal of specific materials without damaging the underlying layers. The sophisticated and reliable Advanced Laser Delivery System (ABDS) allows the selection of different wavelengths to cope with different material cutting and machining requirements. The maximum laser output energy is ≥ 2.7 mJ, and the energy can be adjusted in steps of \geq 300. The water circulation cooling structure makes the system more compact and maintenance-free.

Application

IV/CV characteristics testing and failure analysis of materials/devices, RF characteristics device failure analysis, IC/panel internal circuit modification/delamination, failure analysis lab special

>Advantages of multi-band laser

•Multi-band lasers provide quick IC design, failure analysis, and LCD repairs by switching between different wavelengths according to application requirements. For example, UV light can remove polyimide directly without causing damage to the underlying material. Infrared light can partially penetrate silicon and gallium arsenide to cut through metal lines with minimal damage to the substrate. Green light is the most widely used one, which can effectively cut metal and remove the oxide layer. There are often multiple materials on the device, so multi-band switching is required for different operations.



All actions, including the selection of output energy level, spot size, and wavelength, are done through the remote operation panel, which reduces the chance of bruising the microscope.

Features

• The ability to select different wavelengths to cope with a larger range of material cuts.

•Good laser machining, with good repeatability ranging in size from $50\mu m \times 50\mu m$ (using 50X objective lens, 1064nm band) to $1\mu m \times 1\mu m$ (using 100X objective lens, 532, 355nm band) with good uniformity.

• Continuous fast material cutting (10 seconds of operation at 5 Hz for every 10 seconds of rest), which can be operated intuitively from a remote control panel with LCD menu display panel HI/LO energy level control knob for precise control of a wide range of cutting energies while maintaining optimum beam performance.

• Easy installation and maintenance.



Laser Characteristics	Waveband	Wavelength can choose 1064/532/355/266nm band		
	Power	Output power 2.2mJ/pulse (upgradeable)		
	Micromachining Capability	Processable materials: Cr/Al/ITO/Ni/TFT/RGB/Poly Silicon/Mo/SiN/CF internal impurities, etc.		
	Accuracy	Minimum processing accuracy of 1*1um (when equipped with 100X lens)		
	Cooling method	Air-cooled laser or water-cooled laser can be selected		

>Specifications

11、Shielding box

>Specifications and Features



With grounding terminal

Shielding box door opening method: up-and-over door opening structure (as shown in the figure)

The Left and right sides have 8 holes each for the adapter mounting plate

The concealed cable outlet is at the backside.

The shielding box is independent of the anti-vibration platform design

provide Shielding from light and electromagnetic interference.

Matching probe table and anti-vibration table design.

The probe fixture can test the electrical signal leakage accuracy to 100fa and resist 2000V high voltage.

The shielding box is equipped with adapters to facilitate the good connection of lines inside and outside the box when the shielding box is closed.



12、Dimension

>E8 includes microscope and shockproof table, shielded case form factor

Size: 850mmX650mmX800mm







5、Product Service

Solution consulting service

Our experienced technical experts will provide professional advice on system testing according to your application requirements to help you quickly select satisfactory equipment to purchase.

Warranty service

All SEMISHARE's products have passed strict factory inspection, and we also provide you with professional warranty service.

Technical Training

To help you better understand SEMISHARE products and execute additional application solutions, we can provide customized, systematic technical skills training according to your specific requirements. Please apply to the website or contact us by phone if you require our service.

Product Upgrade Service

Our technology provides value-added services for your products. SEMISHARE can provide hardware and software upgrade services when your testing needs change to help you get more value out of your equipment.

Service Promise

SEMISHARE is committed to responding quickly to your requirements. We will value your every need if you contact us by any means. Online support: 7*24h customer response supported by a professional FAE technical team. Onsite Support:

1) For customers in Shenzhen, after-sales service personnel should arrive at the customer site within 4 hours

2) For customers in Guangdong Province, after-sales service personnel should arrive at the customer site within 24 hours

3) For customers outside Guangdong Province, after-sales service personnel shall arrive at the customer site within48 hours

Service Contact

You can easily reach us or our partners wherever you are.

After-sales Service

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